

PMP8518 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C2	0.68uF	Capacitor, Leaded, Polypropylene R75, 400 Vdc, 20 ±%		R75MN 3680--3M	Kemet / Arcotronics
1	C12	0.1uF	Capacitor, Ceramic, 630V, X7R, 20%	1812	C4532X7R2J104M	TDK
1	C15	18pF	Capacitor, High Voltage Ceramic Disc, 1kVDC, ±10%	0.236 x 0.177 inch	ECCA3A180KGE	Panasonic
1	C20	680pF	Capacitor, Ceramic,50V, COG, 10%	0603	Std	Std
1	C21	150pF	Capacitor, Ceramic, 50-V, COG, 10%	0603	Std	Std
1	C22	5.6nF	Capacitor, Ceramic, 50-V, X7R, 10%	0603	Std	Std
1	C23	470p	Capacitor, Ceramic,50V, [temp], [tol]	0603	std	tdk
1	C24	1u	Capacitor, Ceramic, 10V, [temp], [tol]	0805	std	muRata
1	C25	22u	Capacitor, Aluminum, SM, ±20%, 50V,	D Code	EEEFK1H220P	Panasonic
1	C27	Open	Open	0603	N/A	N/A
1	C28	.01u	Capacitor, Ceramic,50V, [temp], [tol]	0603	std	tdk
1	C40	100uF	Capacitor, Aluminum, 16V, ±20%	0.260 x 0.276 inch	EEEFK1C101P	Panasonic
2	C1 C8	1000pF	Capacitor, Ceramic Disc, 250WV, 1000pF, Y5U ±20%	0.236 x 0.315	ECKNVS102MB	Panasonic
1	C100	2.2uF	Capacitor, Ceramic Chip, xxV, ±10%	1812	Std	Std
1	C101	68uF	Capacitor, Aluminum, 35V, 20%	0.260 x 0.276 inch	EEEFK1V680XP	Panasonic
2	C26 C102	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
2	C3 C7	1000uF	Capacitor, Aluminum Electrolytic, 3.1Arms, 99 milliohm, 200V	1.380 dia * 1.181 inch	ECOS2DB102EA	Panasonic
2	C4-5	0.1uF	Capacitor, Leaded, 0.10 uF, 275 VAC, X2	6x18mm	B81130-C1104-Mxxx	EPCOS
4	C6 C11 C13-14	.1u	Capacitor, Ceramic, 25-V, [temp], [tol]	0603	STD	muRata
4	C9-10 C16-17	470uF	Capacitor, Aluminum, 80V, 160milliohms, MVY type	19mm x 19mm	EMVY800ADA471	Nippon Chemi-Con
1	D2	GBU8J	Diode, Bridge Rectifier, 8 A, 600V	0.880 x 0.140 inch	GBU8J	Fairchild
1	D4	MURS160	Diode, UltraFast Rectifier, 1-A, 600-V	SMB	MURS160T3	On Semi
4	D1 D6-7 D10	BAS40	Diode, Schottky, 200-mA, 40-V	SOT23	BAS40-00-V	Vishay
1	D100	MURA120T3	Diode, UltraFast Rectifier, 1-A, 200-V	403A	MURA120T3	On Semi
1	D102	13V	Diode, Zener, 13-V, 20-mA, 350-mW, 5%	SOT23	Std	Std
1	D103	12V	Diode, Zener, 12-V, 20-mA, 350-mW, 5%	SOT23	Std	Std
3	D12-13 D101	BAS20	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS20-V	Vishay
2	D3 D11	MURS160	Diode, Rectifier,1-A, 600V	SMB	MURS160	on semi
2	D5 D15	LQA16CT300	Diode, UltraFast Rectifier, 16-A, 300-V	TO220AC	LQA16CT300	Power Integration
1	F1	6.3A, Time Lag, 250V	Fuse Clip, 5x20 mm	0.205 x 0.220 inch x2	520	Wickmann
1	J1	703W-00/54	Connector, AC Board mount, 9mm	1.97 x 0.79	703W-00/54	Qualtek Electronics
1	J2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	J3	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
1	L1	2.2mH	Inductor, Common Mode	0.728 x 1083 inch	744824622	Wuerth
1	L2	180uH	Inductor, Vertical, 180uH@7A, 50milliohm	0.860 x 0.450 inch	DBL020406-6 R3311D11	NKL
3	Q1 Q4 Q101	3904	Bipolar, NPN, xx-V, yy-mA, zz-W	SOT23	MMBT3904	Std
1	Q100	PZT2222A	Trans, GP NPN Amplifier, 40Vceo, 1A	SOT-223	PZT2222A	Fairchild
2	Q2 Q5	IRFB16N50K	MOSFET, Nchan, 500V, 17A, 285 millohm	TO-220AB	IRFB16N50K	Vishay
2	Q3 Q6	3906	Bipolar, PNP, xx-V, yy-mA, zz-W	SOT23	MMBT3906	Std
1	R3	470k	Resistor, Chip,1/8-W, yy%	1206	Std	Std
1	R7	220	Resistor, Metal Oxide, 220Ohms, 1W, 5%	0.130 * 0.600 inch	ERG-1SJ221	Panasonic
1	R11	4.7	Resistor, Chip, 1/10-W, 1%	0805	Std	Std

1	R12	1K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R13	49.9	Resistor, Chip, 1/16-W, yy%	0603	Std	Std
1	R14	47.5k	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R16	1k	Resistor, Chip, 1/16-W, yy%	0603	Std	Std
1	R17	35.7K	Resistor, Chip, 1/10-W, yy%	0805	Std	Std
1	R19	4.99k	Resistor, Chip, 1/16W, yy%	0603	Std	Std
1	R20	45.3k	Resistor, Chip, 1/16W, yy%	0603	Std	Std
1	R21	2.49k	Resistor, Chip, 1/16-W, yy%	0603	Std	Std
1	R22	150k	Resistor, Chip, 1/16W, yy%	0603	Std	Std
1	R23	1k	Resistor, Chip, 1/16W, yy%	0603	Std	Std
1	R24	75k	Resistor, Chip, 1/16W, yy%	0603	Std	Std
3	R10 R15 R18	10k	Resistor, Chip, 1/16W, yy%	0603	Std	Std
1	R100	2.2	Resistor, Chip, 1/10-W, 1%	0805	Std	Std
1	R101	7.5k	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R102	10K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
3	R103-105	100k	Resistor, Chip, 0.6W, 1%	2010	STD	STD
3	R1-2 R4	470k	Resistor, Chip, 1/8-W, yy%	1206	Std	Std
2	R5 R8	100	Resistor, Chip, 1/16-W, yy%	0603	Std	Std
2	R6 R60	12k	Resistor, Power , 3 W, 5%	1.300 X .210 inch	Std	Std
1	RT1	275V	Varistor, 275V	0.472 x 0.213 inch	SIOV-S10K275E2	Epcos
1	RT2	2	Thermistor, NTC, 2 ohms, 13.5-A	0.590 x 0.276	B57464S0209M000	Epcos
1	T1	750340157	Transformer, 1 Prim, 1 Sec.	0.455 x 0.455 inch	750340157	WE
1	T2	750885750	Transformer, Forward	43.7mm x 33 mm		WE
1	T3	50:01:00	Transformer, Current Sense, 10A, 100Khz,	0.330 x 0.360 inch	749251050	WURTH
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	TP39		Thru Hole, Tin Plate, for Mounting	0.138 Dia.		STD
15	TP10-11 TP13 TP15	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
1	U2	UCC3813-1D	IC, Low-Power BiCMOS Current-mode PWM, Von = 9.4 V	SO8	UCC3813-1D	TI
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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